

ABSTRACT

To provide a heat-resistant resin composition which has excellent heat resistance, does not show a reduced mechanical strength such as flexural strength even after being passed through a reflow furnace and heat-treated under high temperature conditions, and also has an excellent flame retardancy; a production method of the heat-resistant resin composition; a heat-resistant resin-molded article; and a surface mount electronic component. The heat-resistant resin composition includes a polyarylene sulfide resin (A) and an aromatic polyamide (B) having terephthalic acid amide as an essential structural unit at a former/latter ratio of 70/30 to 95/5 by mass. In a molded article composed of the heat-resistant resin composition, the average diameter of holes formed by etching a broken-out section of the molded article with an organic solvent is 0.1 to 1.0 μm , where the broken-out section is observed on a scanning electron microscope (2,500 times).